

May 1988 Revised January 2004

74F382 4-Bit Arithmetic Logic Unit

General Description

The 74F382 performs three arithmetic and three logic operations on two 4-bit words, A and B. Two additional Select input codes force the Function outputs LOW or HIGH. An Overflow output is provided for convenience in twos complement arithmetic. A Carry output is provided for ripple expansion. For high-speed expansion using a Carry Lookahead Generator, refer to the 74F381 data sheet.

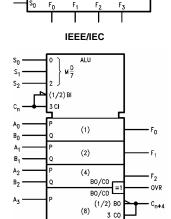
Features

- Performs six arithmetic and logic functions
- Selectable LOW (clear) and HIGH (preset) functions
- LOW input loading minimizes drive requirements
- Carry output for ripple expansion
- Overflow output for twos complement arithmetic

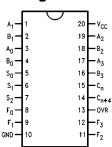
Ordering Code:

Order Number	Package Number	Package Description
74F382SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74F382SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F382PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Logic Symbols



Connection Diagram



Unit Loading/Fan Out

Din Names	Description	U.L.	Input I _{IH} /I _{IL}		
Pin Names	Description	HIGH/LOW	Output I _{OH} /I _{OL}		
A ₀ -A ₃	A Operand Inputs	1.0/4.0	20 μA/–2.4 mA		
B ₀ -B ₃	B Operand Inputs	1.0/4.0	20 μA/-2.4 mA		
S ₀ -S ₂	Function Select Inputs	1.0/1.0	20 μA/-0.6 mA		
C _n	Carry Input	1.0/5.0	20 μA/-3.0 mA		
C _{n + 4}	Carry Output	50/33.3	-1 mA/20 mA		
OVR	Overflow Output	50/33.3	−1 mA/20 mA		
F ₀ -F ₃	Function Outputs	50/33.3	−1 mA/20 mA		

Functional Description

Signals applied to the Select inputs ${\rm S_0-S_2}$ determine the mode of operation, as indicated in the Function Select Table. An extensive listing of input and output levels is shown in the Truth Table. The circuit performs the arithmetic functions for either active HIGH or active LOW operands, with output levels in the same convention. In the Subtract operating modes, it is necessary to force a carry (HIGH for active HIGH operands, LOW for active LOW operands) into the ${\rm C_n}$ input of the least significant package. Ripple expansion is illustrated in Figure 2. The overflow output OVR is the Exclusive-OR of ${\rm C_{n+3}}$ and ${\rm C_{n+4}}$; a HIGH signal on OVR indicates overflow in twos complement operation. Typical delays for Figure 2 are given in Figure 1.

Function Select Table

	Select					
S ₀	S ₁	S ₂	Operation			
L	L	L	Clear			
Н	L	L	B Minus A			
L	Н	L	A Minus B			
Н	Н	L	A Plus B			
L	L	Н	$A \oplus B$			
Н	L	Н	A + B			
L	Н	Н	AB			
Н	Н	Н	Preset			

H = HIGH Voltage Level L = LOW Voltage Level

Beth Commont	Toward	Output
Path Segment	F	C _{n+4} , OVR
A ₁ or B ₁ to C _{n+4}	6.5 ns	6.5 ns
C _n to C _{n+4}	6.3 ns	6.3 ns
C _n to C _{n+4}	6.3 ns	6.3 ns
C _n to F	8.1 ns	_
C_n to C_{n+4} , OVR	_	8.0 ns
Total Delay	27.2 ns	27.1 ns

FIGURE 1. 16-Bit Delay Tabulation

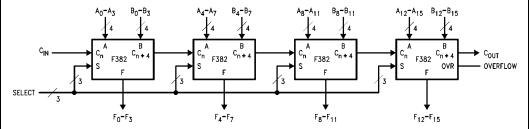
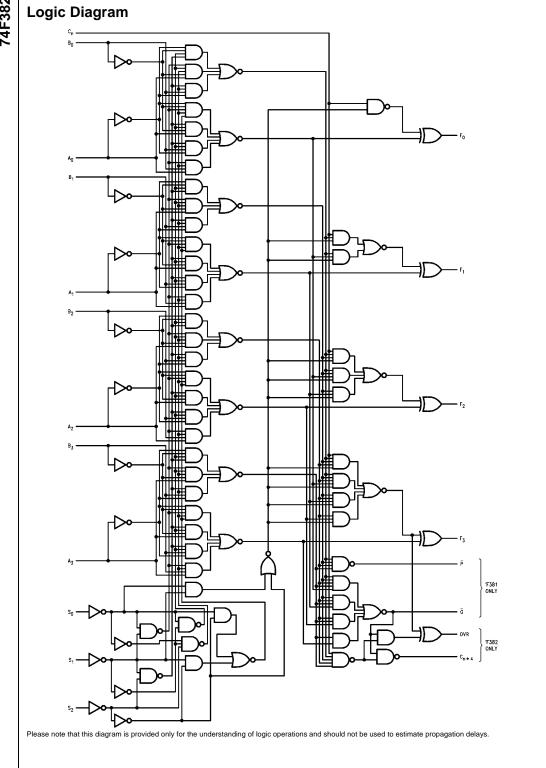


FIGURE 2. 16-Bit Ripply Carry ALU Expansion

Truth Table

				uts			Outputs						
Function	S ₀	S ₁	S ₂	C _n	A _n	B _n	F ₀	F ₁	F ₂	F ₃	OVR	C _{n + 4}	
CLEAR	L	L	L	L	Х	Х	L	L	L	L	Н	Н	
				Н	X	X	L	L	L	L	Н	Н	
B MINUS A	Н	L	L	L	L	L	Н	Н	Н	Н	L	L	
				L	L	Н	L	Н	Н	Н	L	Н	
				L	Н	L	L	L	L	L	L	L	
				L	Н	Н	Н	Н	Н	Н	L	L	
				Н	L	L	L	L	L	L	L	Н	
				Н	L	Н	Н	Н	Н	Н	L	Н	
				Н	Н	L	Н	L	L	L	L	L	
				Н	Н	Н	L	L	L	L	L	Н	
A MINUS B	L	Н	L	L	L	L	Н	Н	Н	Н	L	L	
				L	L	Н	L	L	L	L	L	L	
				L	Н	L	L	Н	Н	Н	L	Н	
				L	Н	Н	Н	Н	Н	Н	L	L	
				Н	L	L	L	L	L	L	L	Н	
				Н	L	Н	Н	L	L	L	L	L	
				Н	Н	L	Н	Н	Н	Н	L	Н	
				Н	Н	Н	L	L	L	L	L	Н	
A PLUS B	Н	Н	L	L	L	L	L	L	L	L	L	L	
				L	L	Н	Н	Н	Н	Н	L	L	
				L	Н	L	н	Н	Н	Н	L	L	
				L	Н	Н	L	Н	Н	Н	L	Н	
				Н	L	L	Н	L	L	L	L	L	
				н	L	Н	L	L	L	L	L	Н	
				н	Н	L	L	L	L	L	L	Н	
				Н	Н	Н	Н	Н	Н	Н	L	Н	
A ⊕ B	L	L	Н	Х	L	L	L	L	L	L	L	L	
				X	L	Н	н	Н	Н	Н	L	L	
				L	Н	L	н	Н	Н	Н	L	L	
				X	Н	Н	L	L	L	L	Н	Н	
				н	Н	L	Н	Н	Н	Н	н	Н	
A + B	Н	L	Н	Х	L	L	L	L	L	L	L	L	
				X	L	Н	Н	Н	Н	H	L	L	
				X	Н	L	H	Н	Н	Н	L	L	
				L	Н	Н	н	Н	Н	Н	L	L	
				Н	Н	Н	Н	Н	Н	Н	н	н	
AB	L	Н	Н	X		L	L	L	L		H	Н	
	-	-	•	X	L	Н	L	L	L	L	L	L	
				X	Н	L	L	L	L	L	H	Н	
				L	н	Н	Н	Н	Н	Н	L	L	
				Н	н	н	Н.	н	Н	Н	Н	Н	
PRESET	Н	Н	Н	X		 L	Н	<u></u> Н	<u></u> Н	 H	L	L	
	''	•••	• • •	X	L	Н	н	н	н	н	L	L	
				X	Н	L	н	н	н	н	L	L	
				L	н	Н	н	н	н	н	L	L	
				Н	Н	Н	Н	н	Н	H	Н	Н	
= HIGH Voltage Le	<u> </u>		Voltage Le		X = Imm		П	п	П	17	ıЛ	П	

H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial



Absolute Maximum Ratings(Note 1)

Conditions

Storage Temperature -65°C to +150°C Ambient Temperature under Bias -55°C to +125°C

Junction Temperature under Bias -55°C to +150°C V_{CC} Pin Potential to Ground Pin -0.5V to +7.0V

Input Voltage (Note 2) -0.5V to +7.0VInput Current (Note 2) -30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with $V_{CC} = 0V$)

Standard Output -0.5V to V_{CC}

3-STATE Output -0.5V to +5.5V

Current Applied to Output

in LOW State (Max) twice the rated I_{OL} (mA) Free Air Ambient Temperature 0°C to +70°C Supply Voltage +4.5V to +5.5V

Recommended Operating

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

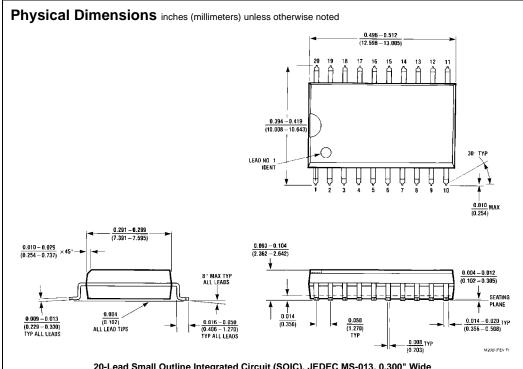
Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics over Operating Temperature Range unless otherwise specified

Symbol	Parameter		Min	Тур	Max	Units	v _{cc}	Conditions	
V _{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal	
V _{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal	
V _{CD}	Input Clamp Diode Voltage				-1.2	V	Min	I _{IN} = -18 mA	
V _{OH}	Output HIGH	10% V _{CC}	2.5			V	Min	I _{OH} = -1 mA	
	Voltage	$5\% V_{CC}$	2.7			V	IVIIII	$I_{OH} = -1 \text{ mA}$	
V _{OL}	Output LOW	10% V _{CC}			0.5	V	Min	1 - 20 mA	
	Voltage	10% vCC			0.5	V	IVIIN	I _{OL} = 20 mA	
I _{IH}	Input HIGH				5.0	μА	Max	V _{IN} = 2.7V	
	Current				5.0	μΛ	IVIAX	V _{IN} = 2.7 V	
I _{BVI}	Input HIGH Current				7.0	μА	Max	V _{IN} = 7.0V	
	Breakdown Test				7.0	μА	IVIAX	$v_{IN} = 7.0v$	
I _{CEX}	Output HIGH Leakage Current				50	μА	Max	V _{OUT} = V _{CC}	
						μΛ	IVIAX		
V _{ID} Input Leakage			4.75			V	0.0	I _{ID} = 1.9 μA	
	Test		4.73			V	0.0	All Other Pins Grounded	
I _{OD}	Output Leakage				3.75	·Δ	0.0	V _{IOD} = 150 mV	
	Circuit Current				3.75	μА	0.0	All Other Pins Grounded	
I _{IL}	Input LOW Current				-0.6			$V_{IN} = 0.5V (S_0 - S_2)$	
					-2.4	mA	Max	$V_{IN} = 0.5V (A_0 - A_3, B_0 - B_3)$	
					-3.0			$V_{IN} = 0.5V (C_n)$	
Ios	Output Short-Circuit Current		-60		-150	mA	Max	V _{OUT} = 0V	
Icc	Power Supply Current			54	81	mA	Max		

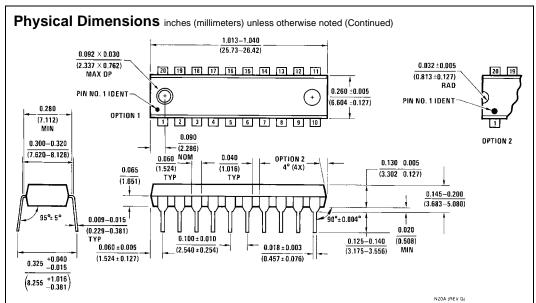
AC Electrical Characteristics

Symbol	Parameter		$T_A = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_1 = 50 \text{ pF}$	1	$T_A = 0^{\circ}C \text{ to } +70^{\circ}C$ $V_{CC} = +5.0V$ $C_1 = 50 \text{ pF}$		Units	
		Min	Тур	Max	Min	Max		
t _{PLH}	Propagation Delay	3.0	8.1	12.0	3.0	13.0		
t _{PHL}	C _n to F _i	2.5	5.7	8.0	2.5	9.0	ns	
t _{PLH}	Propagation Delay	4.0	10.4	15.0	3.5	17.0	ns	
t _{PHL}	Any A or B to Any F	3.0	8.2	11.0	2.5	12.0	115	
t _{PLH}	Propagation Delay	6.5	11.0	20.5	5.5	21.5		
t _{PHL}	S _i to F _i	4.0	8.2	15.0	4.0	17.5	ns	
t _{PLH}	Propagation Delay	3.5	6.0	8.5	3.5	11.0	no	
t _{PHL}	A _i or B _i to C _n + 4	3.5	6.5	9.0	3.5	10.5	ns	
t _{PLH}	Propagation Delay	7.0	12.5	16.5	7.0	17.5	ns	
t _{PHL}	S _i to OVR or C _{n+4}	5.0	9.0	12.0	5.0	14.5	115	
t _{PLH}	Propagation Delay	2.5	5.6	8.0	2.0	9.0	ns	
t _{PHL}	C_n to C_{n+4}	3.5	6.3	9.0	2.0	10.0	115	
t _{PLH}	Propagation Delay	3.5	8.0	11.0	3.5	13.0	ns	
t _{PHL}	C _n to OVR	2.5	7.1	10.0	2.5	11.0	115	
t _{PLH}	Propagation Delay	7.0	11.5	15.5	7.0	16.5	ns	
t _{PHL}	A _i or B _i to OVR	3.0	8.0	10.5	3.0	11.5	115	



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Package Number M20B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 2.6±0.10 0.40 TYP -A-5.01 TYP 5.3±0.10 9.27 TYP 7.8 -B-3.9 0.2 C B A ALL LEAD TIPS 10 PIN #1 IDENT.-0.6 TYP 1.27 TYP -LAND PATTERN RECOMMENDATION ALL LEAD TIPS SEE DETAIL A 0.1 C 2.1 MAX. 1.8±0.1 L 0.15±0.05 0.15-0.25 -1.27 TYP 0.35-0.51 **♦** 0.12 **⋈** C A DIMENSIONS ARE IN MILLIMETERS GAGE PLANE 0.25 NOTES: A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. 0.60±0.15-SEATING PLANE 1.25 -M20DRevB1 DETAIL A 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N20A

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